000	aterial Composit Copyright 2005. IPC, I ernational and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved tions.	under both	This docume level parts, t	ent is a declarat	ion of the su encompasse	ibstances v s all lower	vithin the manufact level materials for	urer listed which the	item. Note: nanufactur	if the item is an as er has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplier Information	n														
Company name* Company u			Company uni	que ID Unid			Unique ID Authority			Respon	Response Date*				
nsemi											2023-00	2023-06-08			
Contact Name			Title - Contact]	Phone - Contact*			Email -	Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA			Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative]	Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards			Product Envir	roduct Enviro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com				
Requester Item	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Effective Date Version Manufacturing Site			Weight*	UOM	Unit Type			
		AR01350 A0-TPBI	CS2M00SUE	1MP 1/3 CIS SO			2023-06-08		T	A1		200.0	mg	Each	
Aanufacturing Proc	cess Information	l													
Terminal Plating / Grid Array Material Terminal Base Al			lloy	J-STD-020 MS	L Rating	Peak Proc	ess Body T	emperature	e Max Time at Pea	ık Tempera	ture Num	ber of Reflow Cy	eles		
SnAgCu CU Alloy				3		260		С	30	seco	nds 3				
omments															
TTENTION: MSL 3 Rat	ted item requires Ba	ke and D	ry Pack (after	electrical test)											
or more information reg	arding material com	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.4	mg		Misc.	proprietary data		0.1231	mg
			Supplier	Silicon (Si)	7440-21-3		31.9561	mg
			Supplier	Aluminum (Al)	7429-90-5		0.3208	mg
Die Attach	2.8	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.05	mg
			Supplier	Ethylene Glycol	107-21-1		0.028	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.084	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.588	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.05	mg
Imaging Lens	28.48	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.4989	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.4989	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.4989	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1501	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.4989	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.4989	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		20.8354	mg
Lid Attach	1.46	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.657	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.292	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.1825	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0073	mg
			Supplier	Curative	Proprietary Data		0.0292	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.292	mg
Mold Compound-Black	65.6	mg		Phenolic Resin	proprietary data		9.84	mg
			Supplier	Oxirane	39817-09-9		9.84	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.968	mg
			Supplier	Carbon Black (C)	1333-86-4		0.656	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.984	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.312	mg
Solder Ball	29.5	mg	Supplier	Silver (Ag)	7440-22-4		0.885	mg
			Supplier	Tin (Sn)	7440-31-5		28.4675	mg
			Supplier	Copper (Cu)	7440-50-8		0.1475	mg
Substrate and Solder Mask	39.48	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.4422	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	5.1166	mg
			Supplier	Zinc (Zn)	7440-66-6	0.0592	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.9199	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.4422	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.229	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0039	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.3779	mg
			Supplier	Carbon Black (C)	1333-86-4	0.229	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.229	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	4.7376	mg
			В	Nickel (Ni)	7440-02-0	0.5567	mg
			Supplier	Gold (Au)	7440-57-5	0.0197	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	2.7597	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.4422	mg
			Supplier	Copper (Cu)	7440-50-8	14.7892	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	7.1261	mg
Wire Bond - Au	0.28	mg	Supplier	Gold (Au)	7440-57-5	0.28	mg